

Copper

SLOTOCOUP CU 140

Copper SLOTOCOUP CU 140 is used for plating but not for filling of blind microvias and is also well suited for metallization of through holes.

The electrolyte deposits bright copper coatings with low internal stress and good ductility and excellent metal distribution.

The metal distribution may be matched to the boards surface geometry by regulation of the current density and electrolyte composition.

Copper SLOTOCOUP CU 140 is operated with three liquid additives. It can be operated with soluble as well as with insoluble anodes.

The information in this data sheet is based on laboratory as well as practical experience. Figures quoted for operating limits and replenishment quantities are for guidance. Actual values necessary will depend on the components being plated (material and geometry), their application and plating plant conditions.

Important:

Please read this instruction carefully prior to the use of the process and carefully follow all the parameters that have a direct influence on the operation. We reserve the right to make technical changes. In the interest of safety, please pay attention to the hazard warnings on the labels of the containers. The minimum shelf life of the products is included on the labels and is also available in the appropriate Quality Assurance (QA03).

The current IMDS number of the layer deposited from the process is available on the internet at www.schloetter.com/downloads.

For the storage of chemical products the TRGS 510 must be followed.

If the additives used in this process contain a SVHC-substance, then this will be specified in the corresponding Material Safety Data Sheet, section 15.

